Double I	Light			
				\neg
	10W F			
	Part N	lo.: DL-PCB5050	ORGBW-10W	
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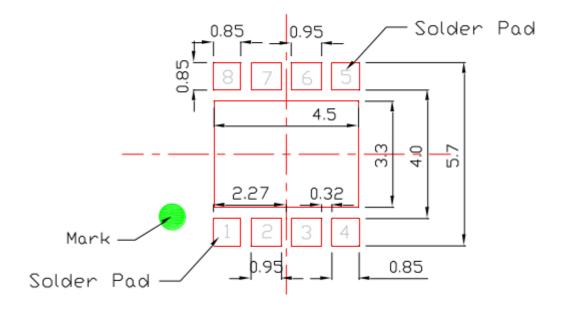
Features:

- 1. Small package with high efficiency
- 2. Long operating life.
- 3. Available in white, green, blue, red, yellow, Amber
- 4. View angle: 120°.
- 5. Low voltage DC operated.
- 6. The product itself will remain within RoHS compliant Version.
- 7. ESD protection.

Applications:

- 1. Reading lights (car, bus, aircraft).
- 2. Portable (flashlight, bicycle).
- 3. Mini accent/Uplighters/Downlighters/Orientation.
- 4. Bollards/Security/Garden.
- 5. Cove/Undershelf/Task.
- 6. Automotive rear combination lamps.
- 7. Traffic signaling/Beacons/ Rail crossing and Wayside.
- 8. Indoor/Outdoor Commercial and Residential Architectural.
- 9. Edge lit signs (Exit, point of sale).
- 10. LCD Backlights/Light Guides.

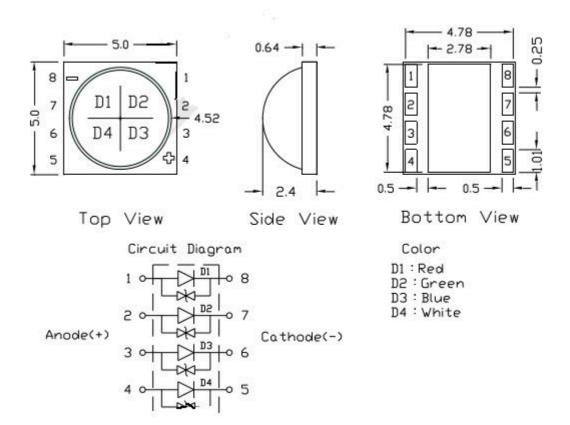
Solder Pad



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Mechanical Dimensions



Part No.	Chip Material		Lens Color	Source Color
	D1	AlGaInP		Hyper Red
DL-PCB5050RGBW-10W	D2	InGaN	Water Clear	Pure Green
	D3	InGaN	Water Clear	Blue
	D4	InGaN		White

Notes:

1. The marked is cathode.

- 2. All dimensions are in millimeters.
- 3. Tolerance is ± 0.25 mm (.010") unless otherwise noted.
- 4. Specifications are subject to change without notice.

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♦ Absolute Maximum Ratings at Ta=25°C

Parameters	Symbol		MAX	Unit		
		Hyper Red	2000	mW		
Daway Dissination	PD	Pure Green	3000			
Power Dissipation		Blue	3000	HIVV		
		White	3000			
		Hyper Red	700			
Peak Forward Current	IFP	Pure Green	700	mA		
(1/10 Duty Cycle, 0.1ms Pulse Width)		Blue	700			
		White	700			
		Hyper Red	350			
Continuous Formand Comment	IF	Pure Green	350	A		
Continuous Forward Current		Blue	350	- mA		
		White	350			
Reverse Voltage	VR		5	V		
		Hyper Red	5000			
Floatus static Dischause (LIDMA)	ESD	Pure Green	5000	V		
Electrostatic Discharge (HBM)		Blue	5000			
		White	5000			
Operating Temperature Range	Topr		-40℃ to +85℃			
Storage Temperature Range		Tstg	-40°C to +100°C			
Soldering Temperature		Tsld	260℃ for 5 Seconds			

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Electrical Optical Characteristics at Ta=25℃

Parameters	Symbol	Emitting Color	Min.	Тур.	Max.	Unit	Test Condition	
		Hyper Red		57		lm	IF=350mA	
Luminous Eluv	Ф	Pure Green		112				
Luminous Flux		Blue		20				
		White	1	140	-			
		Hyper Red	I	108	-			
Luminous Flux	Φ	Pure Green		175		lm	IF=700mA	
Luillillous Flux	Ψ	Blue		35		imi		
		White		240				
	2θ _{1/2}	Hyper Red		120		Deg	IF=350/700mA	
Viowing Anglo		Pure Green		120				
Viewing Angle		Blue		120				
		White		120				
	λр	Hyper Red		632			IF=350/700mA	
Peak Emission Wavelength		Pure Green		520		nm		
Peak Emission wavelength		Blue		468				
		White		6500		k		
	λd	Hyper Red		624				
Dominant Wavelength		pure Green		525		nm	IF=350/700mA	
Dominant wavelength		Blue		470				
		White		6500		k		
	VF	Hyper Red	1.80	2.40	2.80			
Forward Voltage		Pure Green	3.00	3.30	3.80	V	IF=350/700mA	
i oi watu voitage		Blue	3.00	3.30	3.80	v		
		White	3.00	3.30	3.80			

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Reliability Test Items And Conditions:

The reliability of products shall be satisfied with items listed below:

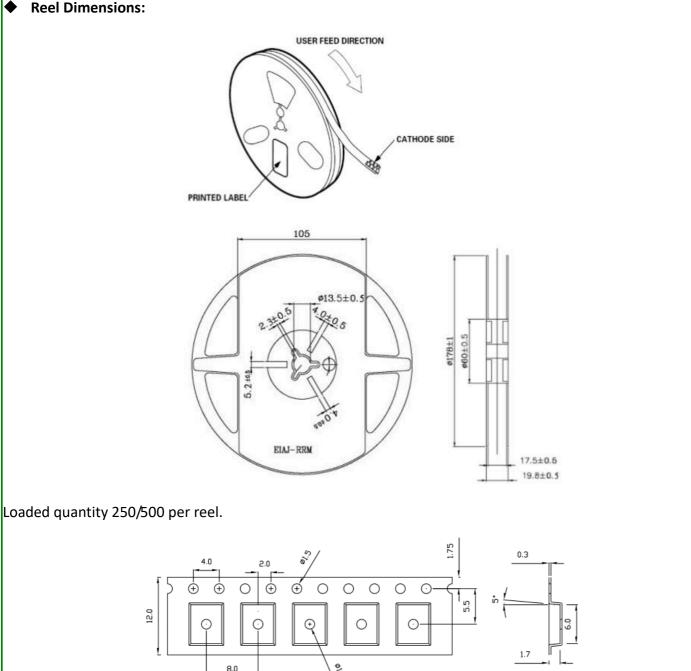
Confidence level: 90%.

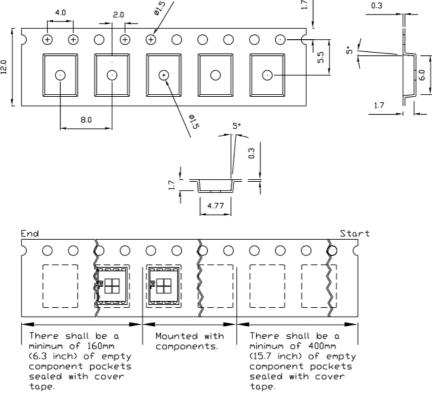
LTPD: 10%.

No.	ltem	Test Conditions	Test Hours/ Cycles	Sample Sizes	Failure Judgment Criteria	Ac/ Re
1	Reflow Soldering	TEMP.: 260℃ <u>+</u> 5℃ 5secs	6mins	22pcs		0/1
2	Temperature Cycle	H: $+100^{\circ}$ C 15mins \int 5 mins \int L: -40° C 15mins IR \geq U*2 Fe \leq L*0.8		IR≧U*2 Ee≦L*0.8	0/1	
3	Thermal Shock	H: $+100^{\circ}\mathbb{C}$ 15mins $ \int $ 10mins $ \int $ L: $-10^{\circ}\mathbb{C}$ 5mins	50Cycles	22pcs	VF ≧ U*1.2 U: Upper Specification	0/1
4	High Temperature Storage	TEMP.: +100℃	1000hrs	22pcs	Limit L: Lower	0/1
5	Lower Temperature Storage	TEMP.: -40°C	1000hrs	22pcs	Specification Limit	0/1
6	DC Operating Life	V _{CE} =5V	1000hrs	22pcs		0/1
7	High Temperature/ High Humidity	85℃ /85% R.H.	1000hrs	22pcs		0/1

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Reel Dimensions:





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Precautions for Use:

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift may cause enormous current change and burn out failure would happen.

- 2. Storage
 - a) Do not open moisture proof bag before the products are ready to use.
 - b) Before opening the package, the Infrareds should be kept at 30° C or less and 90%RH or less.
 - c) The Infrared LED should be used within a year.
 - d) After opening the package, the Infrareds should be kept at 30 $^{\circ}$ C or less and 70%RH or less.
 - e) The Infrared LED should be used within 168 hours (7 days) after opening the package.
 - f) If the moisture absorbent material (silicone gel) has faded away or the Infrareds have exceeded the storage time, baking treatment should be performed using the following conditions.
 - g) Pre-curing treatment: 60±5℃ for 24 hours.
- 3. Thermal Management
 - a) Because the Infrared LED is a high power dissipation device, special and sufficient consideration in thermal management design must be made to optimize the thermal performance.
 - b) Heat sink design is implemented in the device for an additional thermal connection. Since the device is capable of SMT process, tin must be spread both heat sink and solder pads areas to dissipate the heat.
 - c) A high thermal conductivity substrate, such as Aluminum or Copper plate etc, must be applied for external thermal management. It is strongly recommended that the outer heat sink or PCB dimension per Infrared LED can not be less than 25 x 25 x 1 (L x W x H) mm. The materials for outer heat sink can be FR4 on Aluminum, MCPCB, or FPC on Aluminum.
 - d) Special thermal designs are also recommended to take in outer heat sink design, such as FR4 PCB on Aluminum with thermal vias or FPC on Aluminum with thermal conductive adhesive, etc.
 - e) Sufficient thermal management must be conducted, or the die junction temperature will be over the limit under large electronic driving and Infrared LED lifetime will decrease critically.
- 4. Soldering Condition
 - a) Reflow soldering should not be done more than two times.
 - b) While soldering, do not put stress on the Infrareds during heating.
 - c) After soldering, do not warp the circuit board.
- 5. Soldering Iron
 - a) For prototype builds or small series production runs it is possible to place and solder the LED by hand.
 - b) Dispensing thermal conductive glue or grease on the substrates and follow its curing spec. Press Infrared housing to closely connect Infrared and substrate.
 - c) It is recommended to hand solder the leads with a solder tip temperature of 280°C for less than 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal.
 - d) Be careful because the damage of the product is often started at the time of the hand solder.

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